INTEGRATED CIRCUIT PACKAGE BOND PAD HAVING PLURALITY OF CONDUCTIVE MEMBERS

ABSTRACT

An integrated circuit package bond pad includes an insulating layer and an electrode located over the insulating layer. The electrode has a first surface configured to be bonded to external circuitry and a second surface opposite the first surface. A plurality of conductive members is located in the insulating layer, wherein ones of the plurality of conductive members contact the second surface of the electrode.